RELIABILITY REPORT

FOR

MAX4583CUE+T

PLASTIC ENCAPSULATED DEVICES

June 5, 2013

MAXIM INTEGRATED

160 RIO ROBLES

SAN JOSE, CA 95134

Approved by
Sokhom Chum
Quality Assurance
Reliability Engineer

Conclusion

The MAX4583CUE+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX4581/MAX4582/MAX4583 are low-voltage, CMOS analog ICs configured as an 8-channel multiplexer (MAX4581), two 4-channel multiplexers (MAX4582), and three single-pole/double-throw (SPDT) switches (MAX4583). These CMOS devices can operate continuously with ±2V to ±6V dual power supplies or a +2V to +12V single supply. Each switch can handle rail-to-rail analog signals. The off-leakage current is only 1nA at +25°C or 5nA at +85°C. All digital inputs have 0.8V to 2.4V logic thresholds, ensuring TTL/CMOS-logic compatibility when using a single +5V or dual ±5V supplies.

II. Manufacturing Information

A. Description/Function:	Low-Voltage, CMOS Analog Multiplexers/Switches
B. Process:	S3
C. Number of Device Transistors:	65
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines, Thailand, or Malaysia
F. Date of Initial Production:	January 19, 1998

III. Packaging Information

A. Package Type:	16-pin TSSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1201-0105
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	106°C/W
K. Single Layer Theta Jc:	27°C/W
L. Multi Layer Theta Ja:	90°C/W
M. Multi Layer Theta Jc:	27°C/W

IV. Die Information

A. Dimensions:	53X69 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{4.04}{192 \times 4340 \times 80 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 5.82 \times 10^{-9}$

$\lambda = 5.82$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.03 @ 25C and 0.5 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (lot NO7CBA474A, D/C 0431)

The AH14-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-800V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX4583CUE+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 1000 hrs.	DC Parameters & functionality	80	1	NO7BBA762B, D/C 1042

Note 1: Life Test Data may represent plastic DIP qualification lots.